

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT
(Under 37 CFR 1.97(b) or 1.97(c))

Docket No.
BUR920030092US1

In Re Application Of:



Serial No.

10/604,987

Filing Date

08/28/2003

Examiner

Unknown

Group Art Unit

Unknown

Title: **The Use of a Layout-Optimization Tool to Increase the Yield and Reliability of VLSI Designs**

Address to:

**Assistant Commissioner for Patents
Washington, D.C. 20231**

37 CFR 1.97(b)

1. The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application other than a continued prosecution application under 37 CFR 1.53(d); within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; before the mailing of a first Office Action on the merits, or before the mailing of a first Office Action after the filing of a request for continued examination under 37 CFR 1.114.

37 CFR 1.97(c)

2. The Information Disclosure Statement submitted herewith is being filed after the period specified in 37 CFR 1.97(b), provided that the Information Disclosure Statement is filed before the mailing date of a Final Action under 37 CFR 1.113, a Notice of Allowance under 37 CFR 1.311, or an Action that otherwise closes prosecution in the application, and is accompanied by one of:

- the statement specified in 37 CFR 1.97(e);

OR

- the fee set forth in 37 CFR 1.17(p).

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT
 (Under 37 CFR 1.97(b) or 1.97(c))

Docket No.
BUR920030092US1

In Re Application: **Allen et al.**



Serial No.
10/604,987

Filing Date
08/28/2003

Examiner
Unknown

Group Art Unit
Unknown

The Use of a Layout-Optimization Tool to Increase the Yield and Reliability of VLSI Designs

Payment of Fee

(Only complete if Applicant elects to pay the fee set forth in 37 CFR 1.17(p))

- A check in the amount of _____ is attached.
- The Assistant Commissioner is hereby authorized to charge and credit Deposit Account No. **09-0456** as described below. A duplicate copy of this sheet is enclosed.
 - Charge the amount of _____
 - Credit any overpayment.
 - Charge any additional fee required.

Certificate of Transmission by Facsimile*

I certify that this document and authorization to charge deposit account is being facsimile transmitted to the United States Patent and Trademark Office (F)

 (Date)

 Signature

 Typed or Printed Name of Person Signing Certificate

Certificate of Mailing by First Class Mail

I certify that this document and fee is being deposited **09/08/03** with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231. **Alexandria, VA 22313**.

Signature of Person Mailing Correspondence

Typed or Printed Name of Person Mailing Certificate

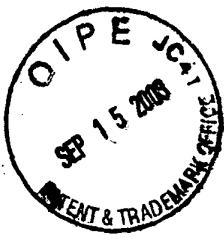
*This certificate may only be used if paying by deposit account.

Richard M. Kotulak
 Signature

Richard M. Kotulak, Reg. No. 27,712
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 IBM Corporation
 1000 River Street
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CC:

Dated: **Sept. 9, 2003**



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of

Allen et al.

Serial No.: ~~Not Yet Assigned~~ 10/604,987 Group Art Unit: Not Yet Assigned

Filing Date: ~~Concurrently Herewith~~ 08/28/2003 Examiner: Unknown

For: THE USE OF A LAYOUT-OPTIMIZATION TOOL TO INCREASE THE YIELD
AND RELIABILITY OF VLSI DESIGNS

Commissioner of Patents
P.O. Box 1450
Alexandria, VA 22313-1450

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Sir:

Under the provisions of 37 CFR §1.97 through §1.99 and pursuant to applicants' duty of disclosure under 37 CFR §1.56, applicants respectfully bring the following documents, listed on the attached form PTO-1449, to the attention of the Examiner in charge of the above-identified application. Copies of the listed documents are provided herewith for the convenience of the Examiner.

This citation does not constitute an admission that the references are relevant or material to the claims. They are only cited as constituting related art of which the applicant is aware.

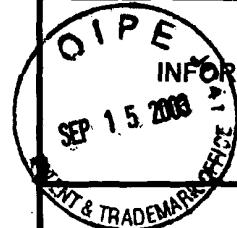
It is respectfully requested that the listed references be considered by the Examiner and formally made of record in this application.

Please charge any deficiencies in fees and credit any overpayment of fees to Attorney's Deposit Account No. 09-0456.

Respectfully submitted,

Frederick W. Gibb, III
Registration No. 37,629

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Customer No. 29154



INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

ATTY DOCKET NO.
BUR920030092US1

SERIAL NO.

FILING
Concurrently Herewith

GROUP

U.S. PATENT DOCUMENTS

FOREIGN PATENT DOCUMENTS

OTHER DOCUMENTS (*Including Author, Title, Date, Pertinent Pages, Etc.*)

		Allan et al., "Automated Redundant Via Placement for Increased Yield and Reliability", Proceedings of the SPIE - The International Society for Optical Engineering Conference, vol. 3216, 1997, pp. 114-125.
		Frank et al., "Yield Improvement of Wafer-Scale Integrated Systolic Structures Via Redundancy", 16th Annual IEEE Electronics and Aerospace Systems Conference and Exposition. 1983, pp. 317-322.

EXAMINER _____ **DATE CONSIDERED** _____

***EXAMINER:** Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

INFORMATION DISCLOSURE CITATION <small>(Use several sheets if necessary)</small> <i>SEP 15 2003</i>				ATTY DOCKET NO. BUR920030092US1	SERIAL NO. Not Yet Assigned		
				FILING Concurrently Herewith	GROUP Unknown		
U.S. PATENT DOCUMENTS							
*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	
FOREIGN PATENT DOCUMENTS							
	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
OTHER DOCUMENTS (<i>Including Author, Title, Date, Pertinent Pages, Etc.</i>)							
		IBM Technical Disclosure, "Yield and Reliability Enhancement Via Redundancy for VLSI Chips and Wafers," vol. 28, No. 1, 1985, pp. 36-42.					
		Chen et al., "Layout Techniques for VLSI Yield Enhancement", Proceedings of the SPIE - The International Society for Optical Engineering Conference", vol. 4600, 2001, pp. 140-147.					
EXAMINER				DATE CONSIDERED			
<small>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</small>							